g		GE Energy		Functional Testing Specification				
	Parts & Repa Louisville, KY	ir Services '		LOU-GED-DS5220CMAF				
	Test Procedure for a							
	DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column							
REV.	Initial release	DESCRIPTION			s Archibald	<b>REV. DATE</b> 06/05/2017		
^	Illitial lelease			Jame	55 AICHIDAIG	00/03/2017		
В								
С								
© COPYRIGHT GENERAL ELECTRIC COMPANY Hard copies are uncontrolled and are for reference only. PROPRIETARY INFORMATION – THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION OF GENERAL ELECTRIC COMPANY AND MAY NOT BE USED OR DISCLOSED TO OTHERS, EXCEPT WITH THE WRITTEN PERMISSION OF GENERAL ELECTRIC COMPANY.								
	ARED BY s Archibald	REVIEWED BY	REVIEWE	D BY	QUALITY APP L. Groves	ROVAL		
<b>DATE</b> 06/05	/2017	DATE	DATE		<b>DATE</b> 6/5/2017			

	g	
LOU-	GE Energy	Page 2 of 3
REV. A	Parts & Repair Services	
	Louisville, KY	

#### 1. SCOPE

**1.1** This is a functional testing procedure for a Card.

# 2. STANDARDS OF QUALITY

**2.1** Refer to the current revision of the IPC-A-610 standard for workmanship standards.

### 3. APPLICABLE DOCUMENTS

- **3.1** The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
  - **3.1.1** Check board's electronic folder for more information

## 4. **ENGINEERING REQUIREMENTS**

- 4.1 Equipment Cleaning
  - **4.1.1** Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.
- **4.2** Equipment Inspection
  - **4.2.1** Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
    - 4.2.1.1 Wires broken, cracked, or loosely connected
    - 4.2.1.2 Terminal strips / connectors broken or cracked
    - 4.2.1.3 Components visually damaged
    - **4.2.1.4** Capacitors bloated or leaking
    - 4.2.1.5 Solder joints damaged or cold
    - 4.2.1.6 Circuit board burned or de-laminated
    - 4.2.1.7 Printed wire runs / Traces burned or damaged

### 5. EQUIPMENT REQUIRED

**5.1** The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 DMM (or Equivalent)
1		Sencor L/C or equivlent

LOUREV. A

GE Energy
Parts & Repair Services
Louis ville, KY

Page 3 of 3

6.	Mod	difica	tions	/Lina	rades
υ.	IVIO	ullica	เนษแร	/UDU	II auts

6.1 Fill out if applicable.

### 7. <u>Testing Process</u>

- 7.1 Setup
  - **7.1.1** Fill out.

Note: None.

- 7.2 Testing Procedure
- 7.3 Using the DS5220CMAF schematic verify all wiring and Resistors are correct.
- 7.4 Using the Sencor 130 L/C meter or equivalent verify appx 13-15 UH.

8.

- 8.1 Post Testing Burn-in Required \_\_\_ Yes \_n\_ No
  - Note: All MARK I, II, & III Turbine related cards require a post testing burn-in of 100 hours.
  - **8.1.1** Apply BUS or Operational power to the card for a period of 100 hours.
  - **8.1.2** Re-test card while warm using the above procedure.
- 8.2 \*\*\*TEST COMPLETE \*\*\*
- 9. Notes
  - **9.1** None at this time?
- 10. Attachments
  - 10.1 None at this time?